

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

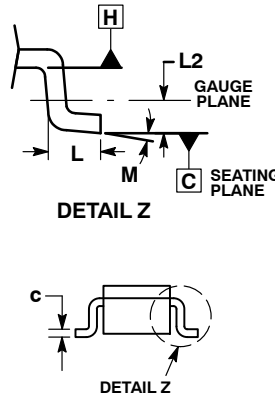
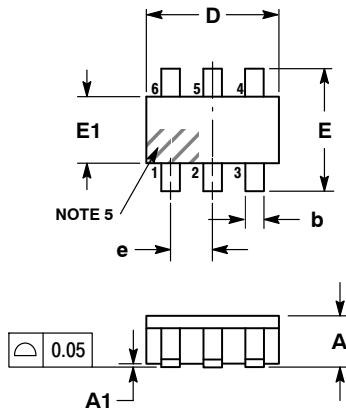
ON Semiconductor®



SCALE 2:1

TSOP-6 CASE 318G-02 ISSUE U

DATE 14 JAN 2010



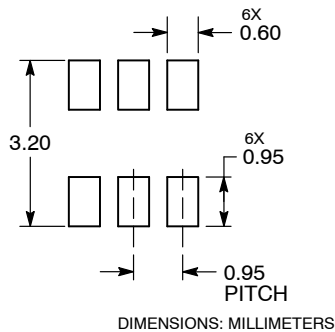
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
5. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.25	0.38	0.50
c	0.10	0.18	0.26
D	2.90	3.00	3.10
E	2.50	2.75	3.00
E1	1.30	1.50	1.70
e	0.85	0.95	1.05
L	0.20	0.40	0.60
L2	0.25 BSC		
M	0°	-	10°

- | | | | | | |
|--|--|---|---|---|--|
| <p>STYLE 1:
PIN 1. DRAIN
2. DRAIN
3. GATE
4. SOURCE
5. DRAIN
6. DRAIN</p> | <p>STYLE 2:
PIN 1. EMITTER 2
2. BASE 1
3. COLLECTOR 1
4. EMITTER 1
5. BASE 2
6. COLLECTOR 2</p> | <p>STYLE 3:
PIN 1. ENABLE
2. N/C
3. R BOOST
4. Vz
5. V in
6. V out</p> | <p>STYLE 4:
PIN 1. N/C
2. V in
3. NOT USED
4. GROUND
5. ENABLE
6. LOAD</p> | <p>STYLE 5:
PIN 1. EMITTER 2
2. BASE 2
3. COLLECTOR 1
4. EMITTER 1
5. BASE 1
6. COLLECTOR 2</p> | <p>STYLE 6:
PIN 1. COLLECTOR
2. COLLECTOR
3. BASE
4. EMITTER
5. COLLECTOR
6. COLLECTOR</p> |
| <p>STYLE 7:
PIN 1. COLLECTOR
2. COLLECTOR
3. BASE
4. N/C
5. COLLECTOR
6. EMITTER</p> | <p>STYLE 8:
PIN 1. Vbus
2. D(in)
3. D(in)+
4. D(out)+
5. D(out)
6. GND</p> | <p>STYLE 9:
PIN 1. LOW VOLTAGE GATE
2. DRAIN
3. SOURCE
4. DRAIN
5. DRAIN
6. HIGH VOLTAGE GATE</p> | <p>STYLE 10:
PIN 1. D(OUT)+
2. GND
3. D(OUT)-
4. D(IN)-
5. VBUS
6. D(IN)+</p> | <p>STYLE 11:
PIN 1. SOURCE 1
2. DRAIN 2
3. DRAIN 2
4. SOURCE 2
5. GATE 1
6. DRAIN 1/GATE 2</p> | <p>STYLE 12:
PIN 1. I/O
2. GROUND
3. I/O
4. I/O
5. VCC
6. I/O</p> |
| <p>STYLE 13:
PIN 1. GATE 1
2. SOURCE 2
3. GATE 2
4. DRAIN 2
5. SOURCE 1
6. DRAIN 1</p> | <p>STYLE 14:
PIN 1. ANODE
2. SOURCE
3. GATE
4. CATHODE/DRAIN
5. CATHODE/DRAIN
6. CATHODE/DRAIN</p> | <p>STYLE 15:
PIN 1. ANODE
2. SOURCE
3. GATE
4. DRAIN
5. N/C
6. CATHODE</p> | | | |

RECOMMENDED SOLDERING FOOTPRINT*



GENERIC MARKING DIAGRAM*



- | | |
|--|---|
| <p>XXX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
■ = Pb-Free Package</p> | <p>XXX = Specific Device Code
M = Date Code
■ = Pb-Free Package</p> |
|--|---|


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TSOP-6	
		PAGE 1 OF 2



ISSUE	REVISION	DATE
B	ADDED STYLE 2. REQ.BY A. PATEL.	05 MAY 1997
C	ADDED STYLE 3. REQ.BY D. BOLDT, ADDED STYLE 4. REQ.BY UKO.	14 APR 1998
D	ADDED STYLE 5. REQ.BY D. BOLDT.	13 MAY 1998
E	ADDED STYLE 6. REQ.BY M. ATANOVICH.	17 NOV 1999
F	MOTOROLA WAS NOT REMOVED FROM (STATUS) PAGES. PAGES NOT NUMBERED CORRECTLY. REV PAGE WAS MISSING. REQ.BY F. BLAKLEY.	22 NOV 1999
G	ADDED STYLE 7. REQ.BY M. ATANOVICH.	15 DEC 1999
H	ADDED STYLE 8. REQ.BY D. TRUHITTE.	11 MAY 2001
J	ADDED NOTE 4. REQ. BY S. RIGGS.	26 JUN 2003
K	ADDED STYLE 9. REQ.BY S. BACHMAN.	09 SEP 2003
L	ADDED STYLE 10. REQ. BY A. TAM.	25 FEB 2004
M	ADDED STYLE 11 AND 12. REQ. BY L. ROBINSON.	07 JUN 2004
N	CORRECTED STYLE 11, PIN 4 SOURCE 2. REQ. BY C. CHENG .	03 FEB 2005
P	ADDED NOMINAL VALUES AND UPDATED GENERIC MARKING DIAGRAM. REQ. BY HONG XIAO.	27 MAY 2005
R	ADDED STYLE 13. REQ. BY J. CARTER.	09 MAR 2006
S	ADDED STYLE 14. REQ. BY A. SAM.	22 MAR 2006
T	ADDED STYLE 15. REQ. BY S. WINSTON.	06 FEB 2008
U	ADDED DETAIL Z, REMOVED INCH VALUES, ADDED L2, ADDED NOTE 5. REQ. BY J. LETTERMAN.	14 JAN 2010

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